

## Features

- Ideally Suited for Automatic Insertion
- Epitaxial Planar Die Construction
- Complementary PNP Types Available (BC807)
- For switching and AF Amplifier Applications
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **Automotive-Compliant Parts Are Available Under Separate Datasheet ([BC817-16Q\\_40Q](#))**

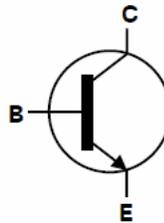
## Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 Ⓜ3
- Weight 0.008 grams (Approximate)

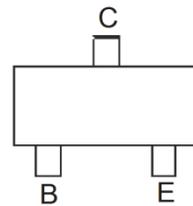
SOT23



Top View



Device Symbol



Top View  
Pin-Out

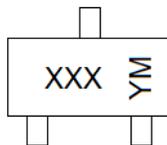
## Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
BC817-16-7-F	AEC-Q101	K6A	7	8	3,000
BC817-25-7-F	AEC-Q101	K6B	7	8	3,000
BC817-40-7-F	AEC-Q101	K6C	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information

SOT23



XXX = Product Type Marking Code (See Table Above)  
 YM = Date Code Marking  
 Y = Year (ex: C = 2015)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026
Code	C	D	E	F	G	H	I	J	K	L	M	N

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CB0</sub>	50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	45	V
Emitter-Base Voltage	V <sub>EBO</sub>	5.0	V
Collector Current	I <sub>C</sub>	0.5	A
Peak Collector Current	I <sub>CM</sub>	1.0	A
Peak Base Current	I <sub>BM</sub>	200	mA

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

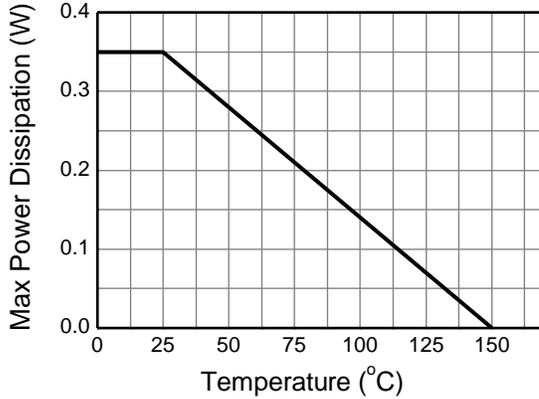
Characteristic	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	(Note 5)	310
		(Note 6)	350
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	(Note 5)	403
		(Note 6)	357
Thermal Resistance, Junction to Leads	R <sub>θJL</sub>	350	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**ESD Ratings** (Note 8)

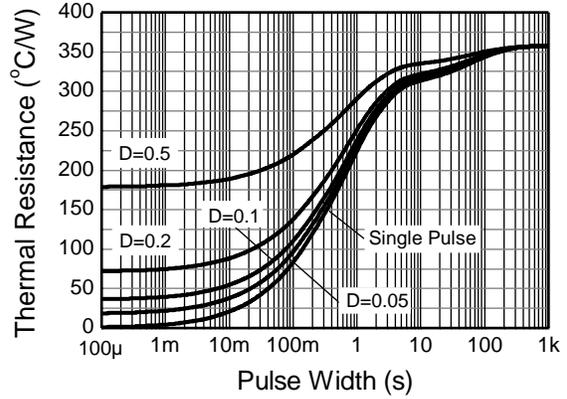
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted on minimum recommended pad layout FR-4 PCB with high coverage of single sided 1oz copper; device is measured under still air conditions whilst operating in a steady-state.
  6. Same as Note 5, except mounted on 15mm x 15mm 1oz copper.
  7. Thermal resistance from junction to solder-point (at the end of the collector lead).
  8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

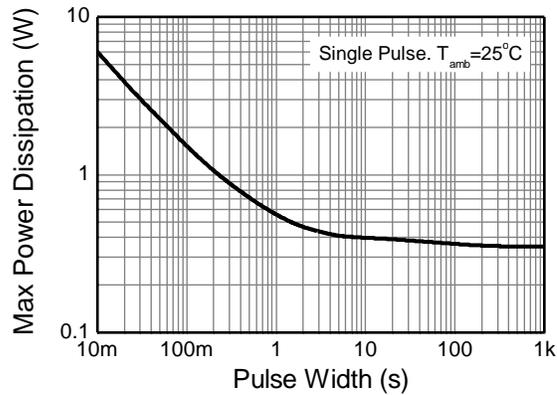
**Thermal Characteristics and Derating Information**



**Derating Curve**



**Transient Thermal Impedance**



**Pulse Power Dissipation**

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage		BV <sub>CBO</sub>	50	—	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage		BV <sub>CEO</sub>	45	—	—	V	I <sub>C</sub> = 10mA
Emitter-Base Breakdown Voltage		BV <sub>EBO</sub>	5	—	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Cut-Off Current		I <sub>CES</sub>	—	—	100 5.0	nA μA	V <sub>CE</sub> = 45V V <sub>CE</sub> = 25V, T <sub>J</sub> = +150°C
Emitter-Base Cut-Off Current		I <sub>EBO</sub>	—	—	100	nA	V <sub>EB</sub> = 5.0V
DC Current Gain (Note 9)	BC817-16 BC817-25 BC817-40	h <sub>FE</sub>	100 160 250	—	250 400 600	—	V <sub>CE</sub> = 1.0V, I <sub>C</sub> = 100mA
	BC817-16 BC817-25 BC817-40		60 100 170		—		
Collector-Emitter Saturation Voltage (Note 9)		V <sub>CE(SAT)</sub>	—	—	0.7	V	I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
Base-Emitter Voltage (Note 9)		V <sub>BE</sub>	—	—	1.2	V	V <sub>CE</sub> = 1.0V, I <sub>C</sub> = 300mA
Gain Bandwidth Product		f <sub>T</sub>	100	—	—	MHz	V <sub>CE</sub> = 5.0V, I <sub>C</sub> = 10mA, f = 50MHz
Collector-Base Capacitance		C <sub>CBO</sub>	—	—	12	pF	V <sub>CB</sub> = 10V, f = 1.0MHz

Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

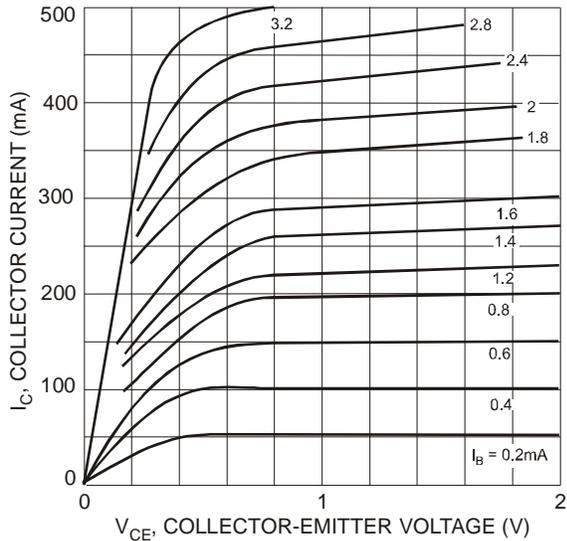


Figure 1 Typical Collector Current vs. Collector-Emitter Voltage

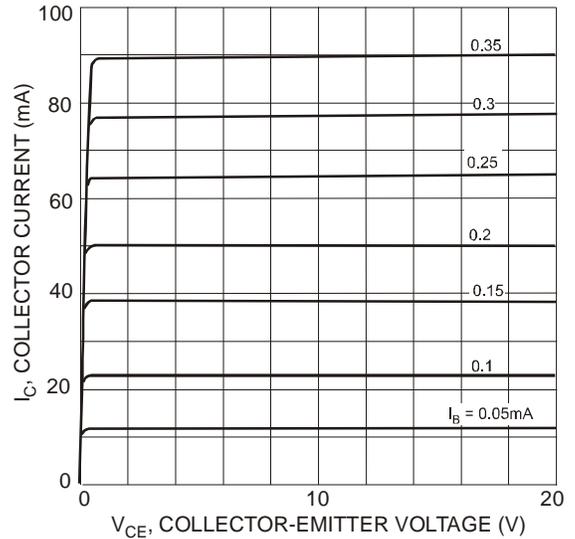


Figure 2 Typical Collector Current vs. Collector-Emitter Voltage

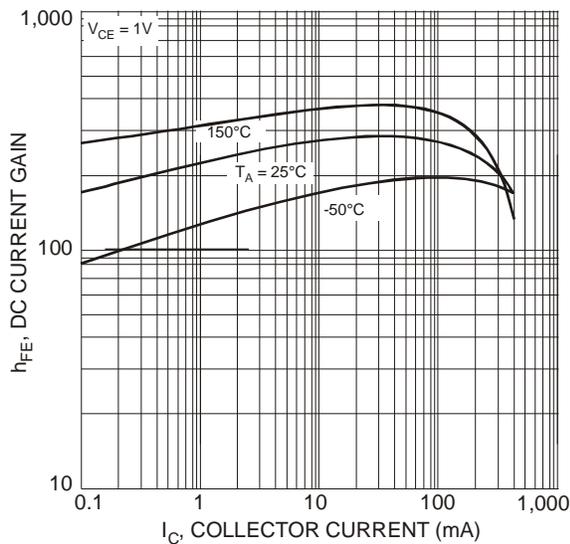


Figure 3 Typical DC Current Gain vs. Collector Current

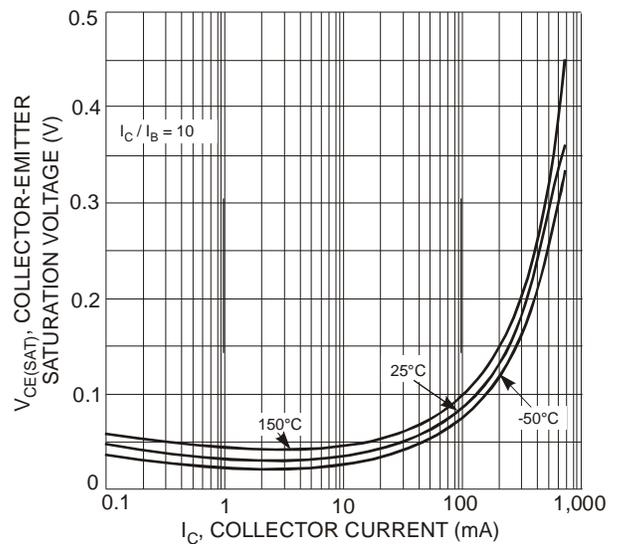


Figure 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

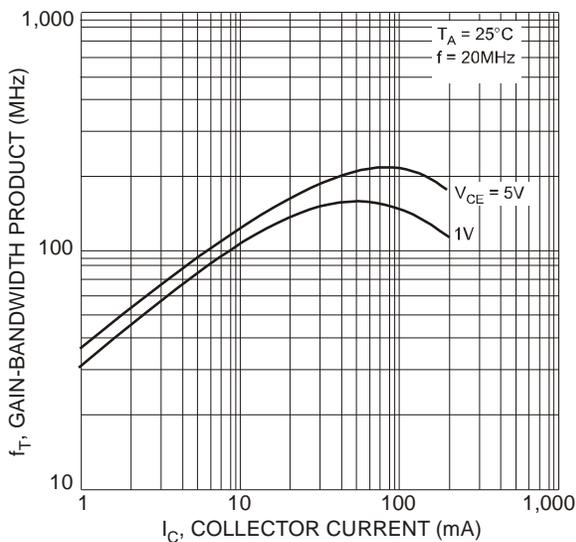
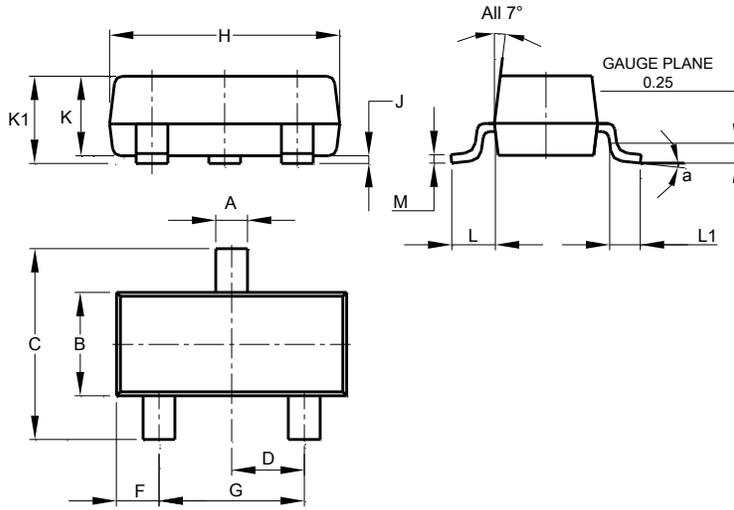


Figure 5 Gain-Bandwidth Product vs. Collector Current

**Package Outline Dimensions**

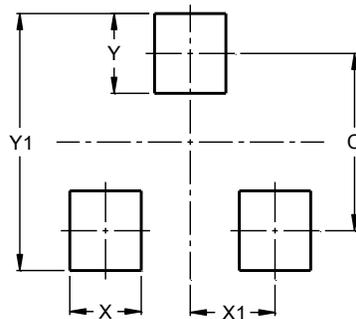
Please see AP02001 at [http://www.diodes.com/\\_files/datasheets/ap02001.pdf](http://www.diodes.com/_files/datasheets/ap02001.pdf) for the latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at [http://www.diodes.com/\\_files/datasheets/ap02001.pdf](http://www.diodes.com/_files/datasheets/ap02001.pdf) for the latest version.



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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